

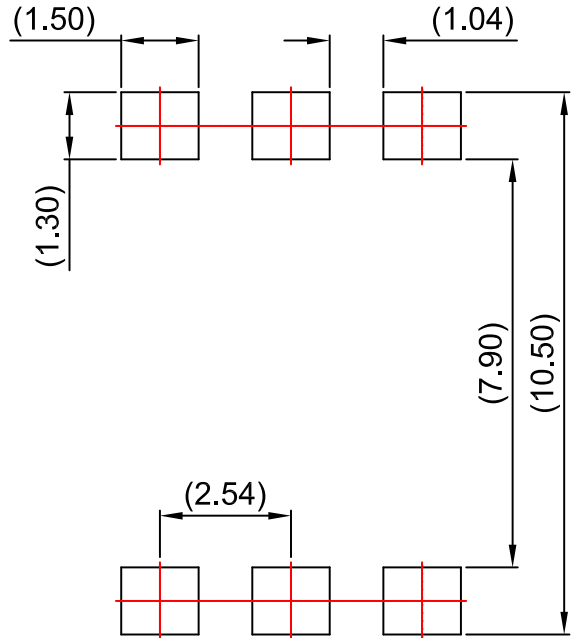
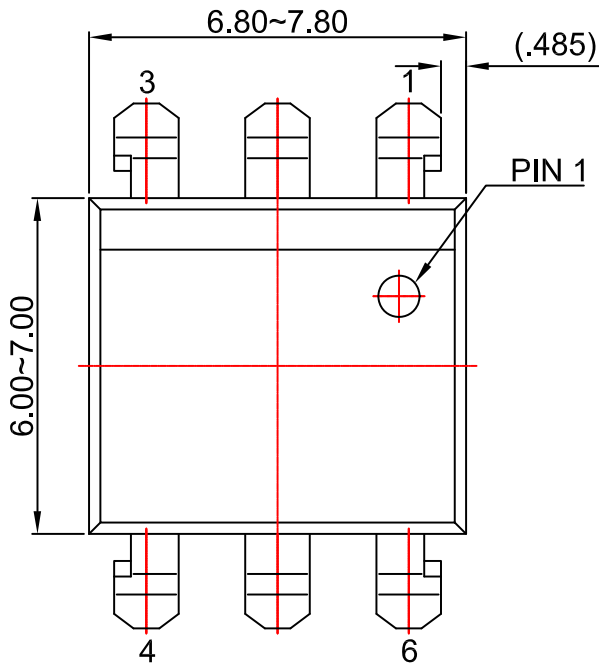
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

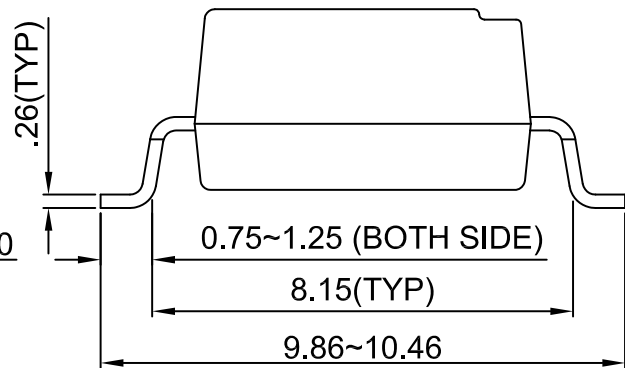
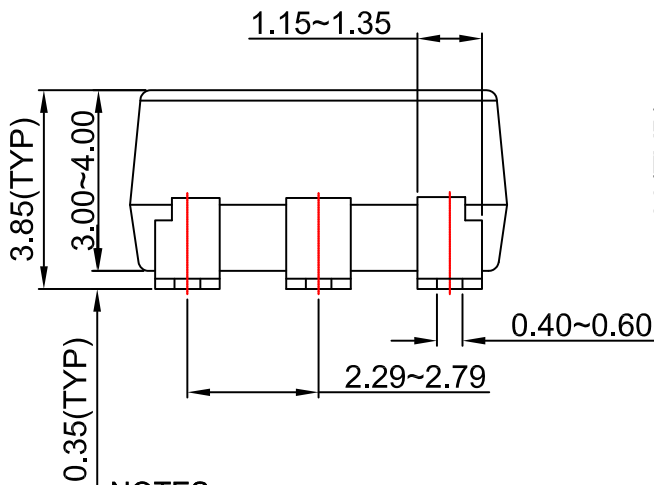


PDIP6 7.3x6.5, 2.54P
CASE 646CE
ISSUE O

DATE 31 JUL 2016



LAND PATTERN RECOMMENDATION



NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION

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NEW STANDARD:		
DESCRIPTION:	PDIP6 7.3X6.5, 2.54P	PAGE 1 OF 2

